

2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

MECHANICAL DATA

• Case: SOD-123FL

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Meet JESD 201 class 1 whisker test

Polarity: Indicated by cathode band

Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	2	Α	
V_{RRM}	200 - 1000	V	
I _{FSM}	40	Α	
T _{J MAX}	150	°C	
Package	SOD-123FL		
Configuration	Single die		









SOD-123FL



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DFL	RS2GFL	RS2JFL	RS2KFL	RS2MFL	UNIT
Marking code on the device			R2DF	R2GF	R2JF	R2KF	R2MF	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F	2				Α	
Surge peak forward current, single half sine-		I	40					А
wave superimposed on rated load	t = 1.0ms	I _{FSM}	100					А
Junction temperature		T_J	-55 to +150					°C
Storage temperature		T_{STG}	-55 to +150				°C	





THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R _{OJL}	81	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	116	°C/W	
Junction-to-case thermal resistance	R _{eJC}	69	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 1A, T _J = 25°C		0.86	-	V
	RS2DFL	I _F = 2A, T _J = 25°C]	0.94	1.30	V
	RS2GFL	I _F = 1A, T _J = 125°C	V_{F}	0.75	-	V
5 (1)		I _F = 2A, T _J = 125°C]	0.84	0.99	V
Forward voltage ⁽¹⁾		I _F = 1A, T _J = 25°C		0.98	-	V
	RS2JFL	I _F = 2A, T _J = 25°C	V _F	1.09	1.30	V
	RS2KFL RS2MFL	I _F = 1A, T _J = 125°C		0.89	-	V
		I _F = 2A, T _J = 125°C		1.02	1.20	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	5	μA
		T _J = 125°C	- I _R	-	150	μA
RS2DFL RS2GFL		1 050 1 100		-	150	ns
Reverse recovery time	RS2JFL RS2KFL RS2MFL	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t _{rr}	-	250	ns
	RS2DFL RS2GFL		CJ	16	-	pF
Junction capacitance	RS2JFL RS2KFL RS2MFL	1MHz, $V_R = 4.0V$		9	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
RS2xFL	SOD-123FL	10,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(RS2DFL) to 1000V(RS2MFL)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

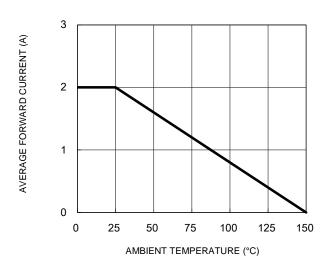


Fig.3 Typical Reverse Characteristics

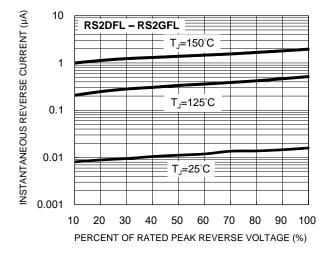


Fig.5 Typical Reverse Characteristics

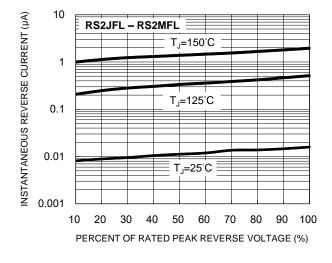


Fig.2 Typical Junction Capacitance

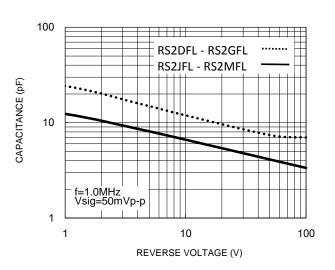


Fig.4 Typical Forward Characteristics

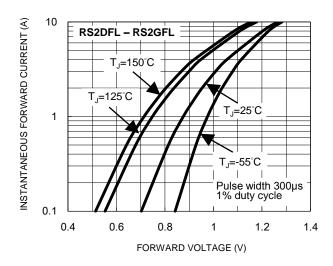
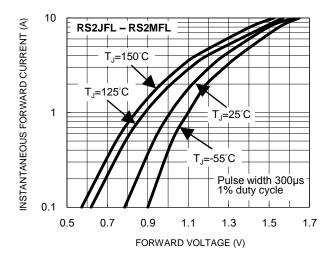


Fig.6 Typical Forward Characteristics

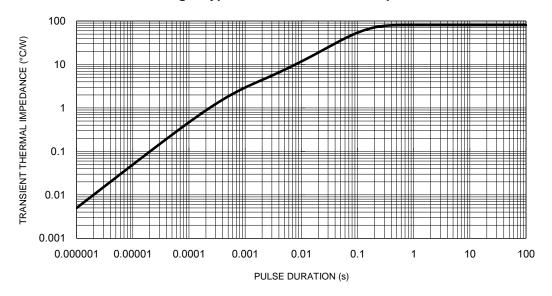




CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

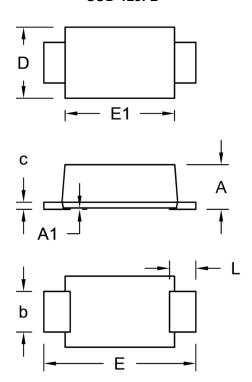
Fig.7 Typical Transient Thermal Impedance





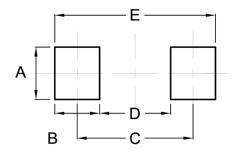
PACKAGE OUTLINE DIMENSIONS

SOD-123FL



DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	1.00	1.20	0.039	0.047
A1	0.02	0.05	0.001	0.002
b	0.90	1.10	0.035	0.043
С	0.10	0.25	0.004	0.010
D	1.60	1.90	0.063	0.075
E	3.60	3.90	0.142	0.154
E1	2.55	2.85	0.100	0.112
L	0.40	0.90	0.016	0.035

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

MARKING DIAGRAM



P/N = Marking Code = Date Code ΥW F = Factory Code



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